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(54) **LIQUID-COOLING DEVICES, AND  
SYSTEMS, TO COOL MULTI-CHIP  
MODULES**

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(57) **ABSTRACT**

A heat exchanger for a liquid cooling system has an enclosure defining an internal chamber and a wall defining an external major surface of the enclosure. The enclosure extends from a first open end to an opposed second open end and an inlet passage extends from the first open end to the internal chamber. An outlet passage extends from the internal chamber to the second open end. A plurality of corrugated fins are conductively coupled with the wall defining the external major surface and positioned in the internal chamber. A liquid cooling system can include such a heat exchanger. And, an electronic device can include one or more multichip modules cooled by such a cooling system.

